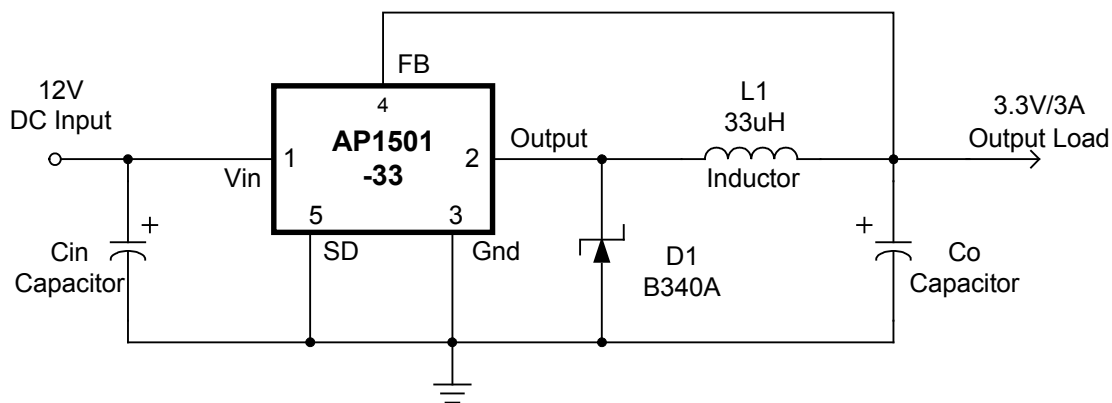


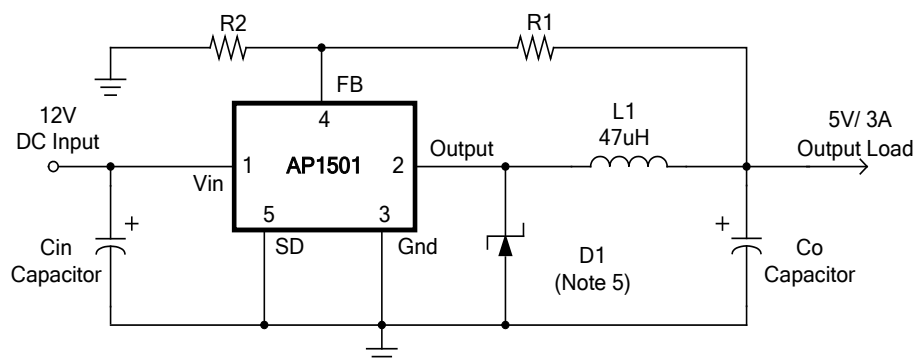
Typical Applications Circuit

(1) Fixed Type Circuit



Typical Applications Circuit (continued)

(2) Adjustable Type Circuit

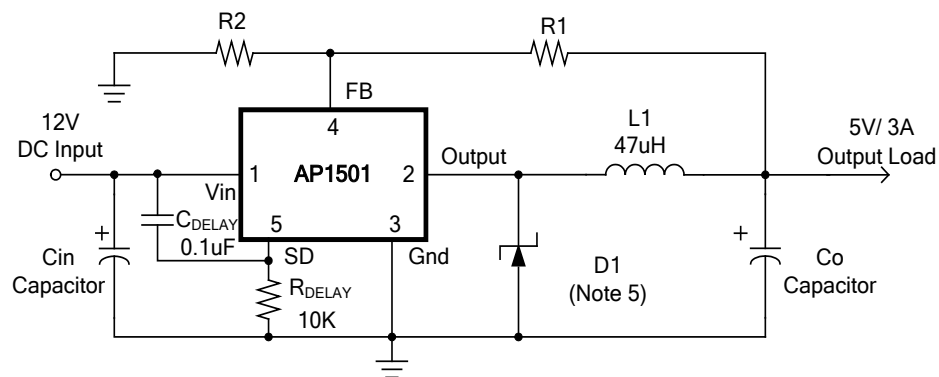


$$V_{out} = V_{FB} \times \left(1 + \frac{R1}{R2}\right)$$

$$V_{FB} = 1.23V$$

$$R2 = 1K \sim 3K$$

(3) Delay Start Circuit

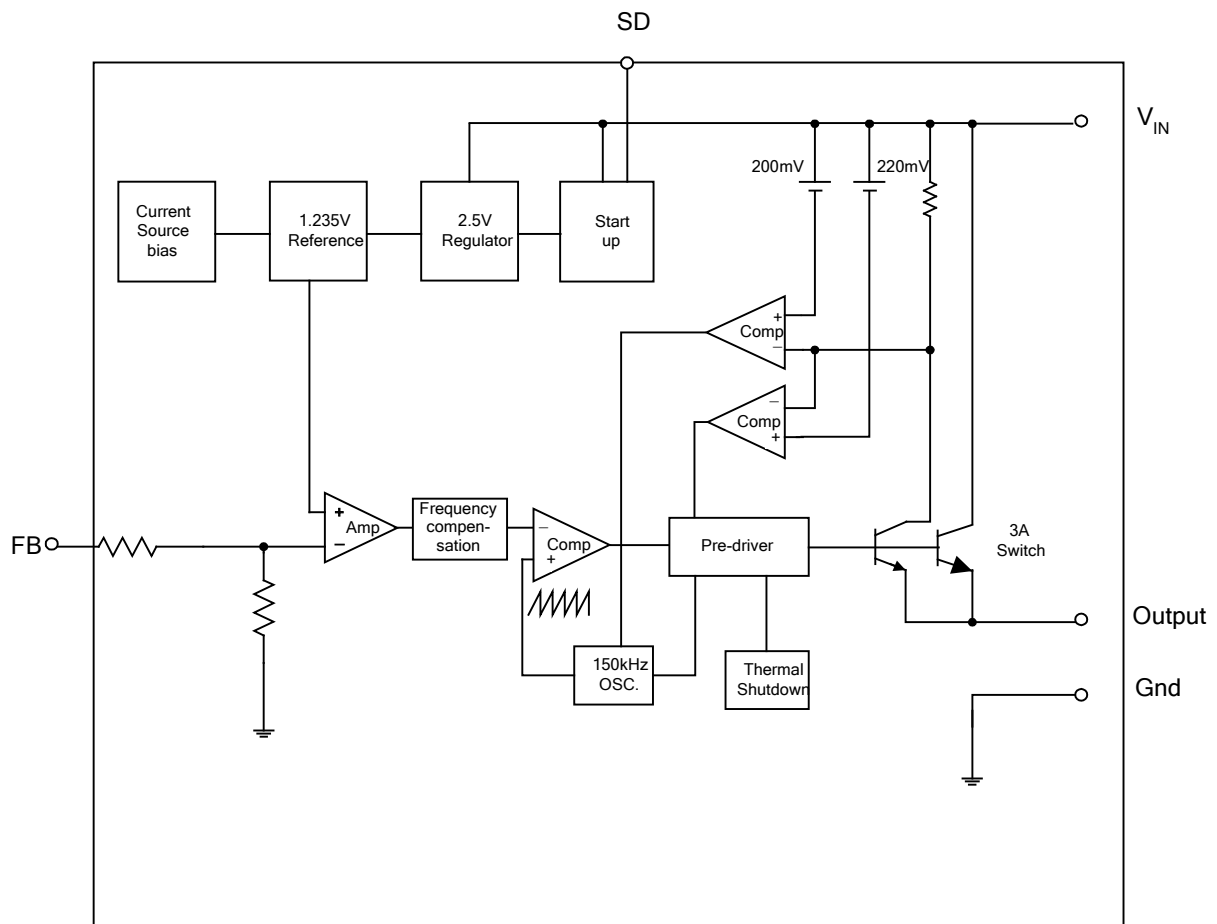


Note: Suggested Diodes Incorporated's Power Schottky: B340A or PDS340 series.

Pin Descriptions

Name	Description
V _{IN}	Operating Voltage Input
Output	Switching Output
Gnd	Ground
FB	Output Voltage Feedback Control
SD	ON/OFF Shutdown

Functional Block Diagram



Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
ESD MM	Machine Model ESD Protection	400	V
V _{CC}	Supply Voltage	+45	V
V _{SD}	ON/OFF Pin Input Voltage	-0.3 to +40	V
V _{FB}	Feedback Pin Voltage	-0.3 to +40	V
V _{OUT}	Output Voltage to Ground	-1	V
P _D	Power Dissipation	Internally Limited	W
T _{ST}	Storage Temperature	-65 to +150	°C
T _J	Operating Junction Temperature	-20 to +125	°C
T _{MJ}	Maximum Junction Temperature	+150	°C

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Unless otherwise specified, $V_{IN} = 12\text{V}$ for 3.3V, 5V, adjustable version and $V_{IN} = 24\text{V}$ for the 12V version. $I_{LOAD} = 0.5\text{A}$
Specifications with **boldface type** are for full operating temperature range, the other type are for $T_J = +25^\circ\text{C}$.

Symbol	Parameter		Conditions	Min	Typ.	Max	Unit
I _{FB}	Feedback Bias Current		V _{FB} = 1.3V (Adjustable Version Only) (Note 4)	—	40	60 100	nA
F _{OSC}	Oscillator Frequency		—	127 110	150 —	173 173	kHz
V _{SAT}	Saturation Voltage		I _{OUT} = 3A No Outside Circuit V _{FB} = 0V Force Driver On	—	1.3	1.4 1.5	V
DC	Max. Duty Cycle (ON)		V _{FB} = 0V Force Driver On	—	100	—	%
	Min. Duty Cycle (OFF)		V _{FB} = 12V Force Driver Off	—	0	—	
I _{CL}	Current Limit		Peak Current No Outside Circuit V _{FB} = 0V Force Driver On	3.6	4.0	5.5 6.5	A
I _L	Output = 0	Output Leakage Current	—	—	200	200	μA
	Output = -1		—	2	60	60	mA
I _Q	Quiescent Current		V _{FB} = 12V Force Driver Off	—	5	10	mA
I _{STBY}	Standby Quiescent Current		ON/OFF Pin = 5V V _{IN} = 40V	—	150	250 350	μA
V _{IL}	ON/OFF Pin Logic Input Threshold Voltage		Low (Regulator ON)	—	1.3	0.6	V
V _{IH}			High (Regulator OFF)	2.0		—	
I _H	ON/OFF Pin Logic Input Current		V _{LOGIC} = 2.5V (OFF)	—	15	25	μA
I _L	ON/OFF Pin Input Current		V _{LOGIC} = 0.5V (ON)	—	0.02	5	
θ _{JA}	Thermal Resistance Junction to Ambient		TO263-5 (Note 5)	—	37	—	°C/W
			TO220-5 (Note 5)	—	31	—	
θ _{JC}	Thermal Resistance Junction to Case		TO263-5 (Note 5)	—	6	—	°C/W
			TO220-5 (Note 5)	—	5	—	

Notes: 4. Feedback pin removed from output and connected to 0V to force the output transistor switch ON. Feedback pin removed from output and connected to 12V for the 3.3V, 5V, and the ADJ. version, and 15V for the 12V version, to force the output transistor switch OFF.
5. Test condition: Device mounted with copper area of approximately 3 in^2 , 1oz, no air flow.

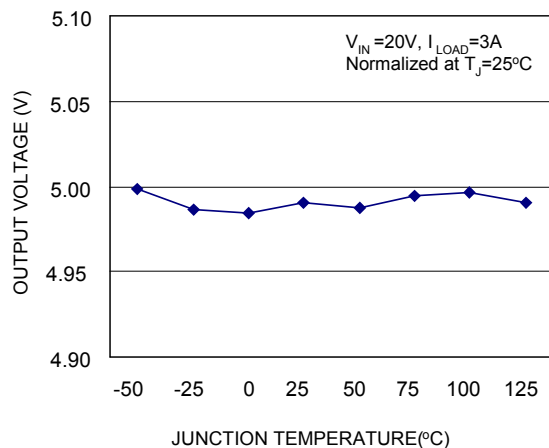
Electrical Characteristics (continued) (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Specifications with **boldface type** are for full operating temperature range, the other type are for $T_J = +25^\circ\text{C}$.

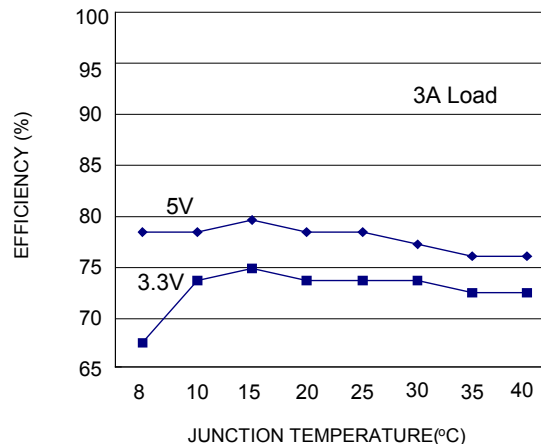
—	Symbol	Parameter	Conditions	V_{Min}	Typ.	V_{Max}	Unit
AP1501-ADJ	V_{FB}	Output Feedback	$4.5\text{V} \leq V_{\text{IN}} \leq 40\text{V}$ $0.2\text{A} \leq I_{\text{LOAD}} \leq 3\text{A}$ V_{OUT} programmed for 3V	1.193 1.18	1.23	1.267 1.28	V
	η	Efficiency	$V_{\text{IN}} = 12\text{V}$, $I_{\text{LOAD}} = 3\text{A}$	—	73	—	%
AP1501-3.3V	V_{OUT}	Output Voltage	$4.75\text{V} \leq V_{\text{IN}} \leq 40\text{V}$ $0.2\text{A} \leq I_{\text{LOAD}} \leq 3\text{A}$	3.168 3.135	3.3	3.432 3.465	V
	η	Efficiency	$V_{\text{IN}} = 12\text{V}$, $I_{\text{LOAD}} = 3\text{A}$	—	73	—	%
AP1501-5V	V_{OUT}	Output Voltage	$7\text{V} \leq V_{\text{IN}} \leq 40\text{V}$ $0.2\text{A} \leq I_{\text{LOAD}} \leq 3\text{A}$	4.8 4.75	5	5.2 5.25	V
	η	Efficiency	$V_{\text{IN}} = 12\text{V}$, $I_{\text{LOAD}} = 3\text{A}$	—	80	—	%
AP1501-12V	V_{OUT}	Output Voltage	$15\text{V} \leq V_{\text{IN}} \leq 40\text{V}$ $0.2\text{A} \leq I_{\text{LOAD}} \leq 3\text{A}$	11.52 11.4	12	12.48 12.6	V
	η	Efficiency	$V_{\text{IN}} = 15\text{V}$, $I_{\text{LOAD}} = 3\text{A}$	—	90	—	%

Performance Characteristics

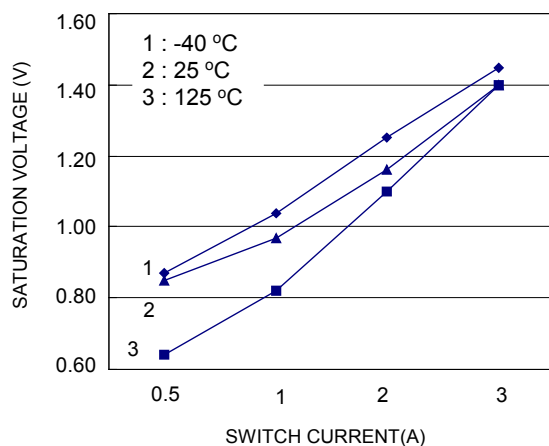
Typical Performance Characteristics
Normalized Output Voltage



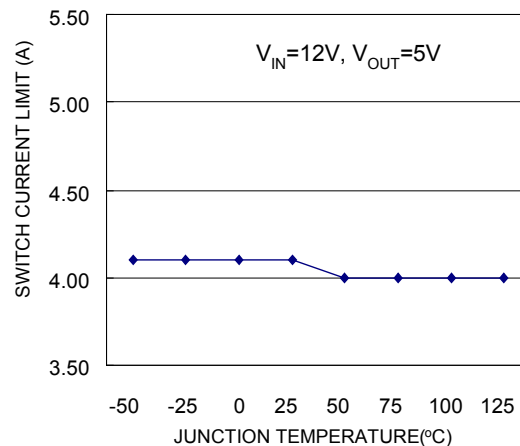
Efficiency



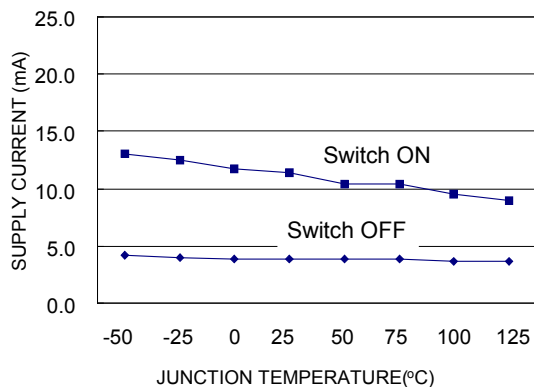
Switch Saturation Voltage



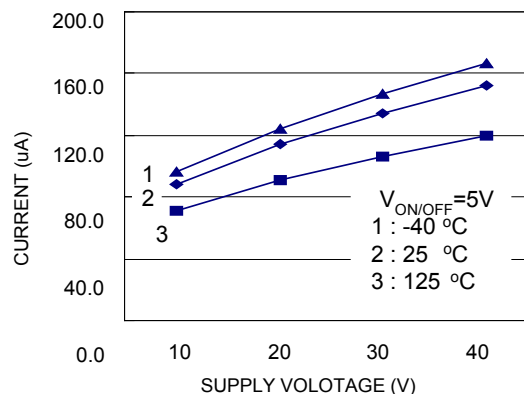
Switch Current Limit



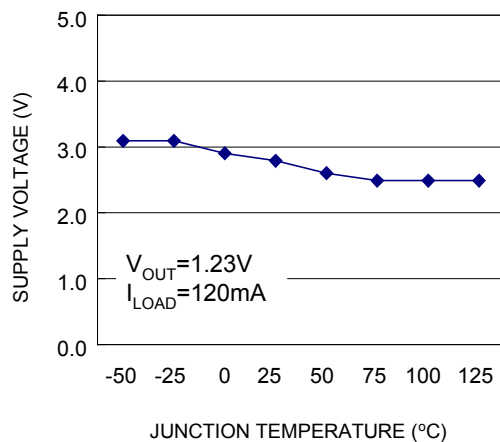
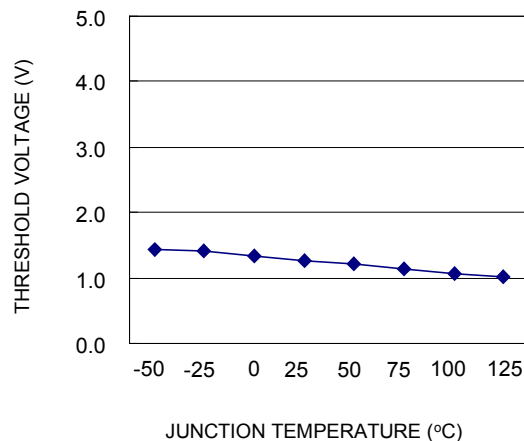
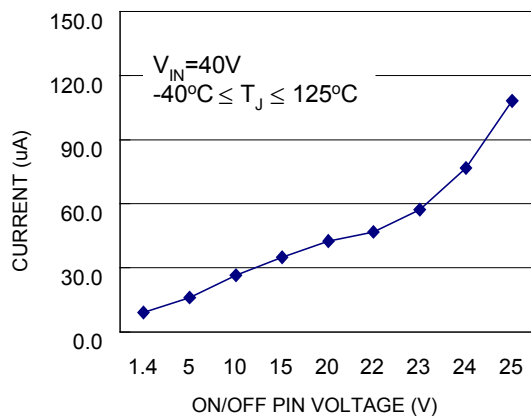
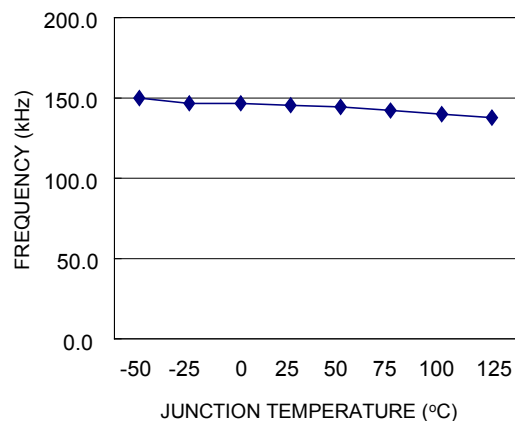
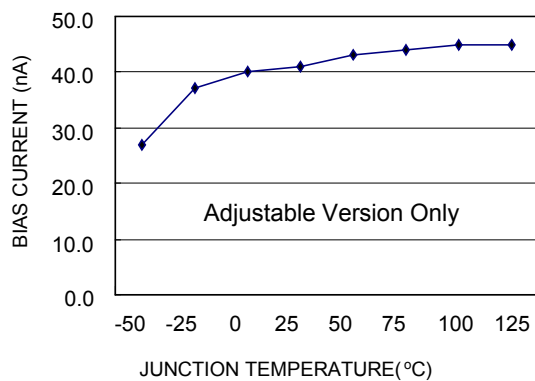
Operating Quiescent Current



Shutdown Quiescent Current



Performance Characteristics (continued)

Minimum Operating Supply Voltage

ON/OFF Threshold Voltage

ON/OFF Pin Current (Sinking)

Switch Frequency

Feedback Pin Bias Current


Operation Description

Pin Functions

+V_{IN}

This is the positive input supply for the IC switching regulator. A suitable input bypass capacitor must be present at this pin to minimize voltage transients and to supply the switching currents needed by the regulator.

Ground

Circuit ground.

Output

Internal switch. The voltage at this pin switches between $(+V_{IN} - V_{SAT})$ and approximately $-0.5V$, with a duty cycle of approximately V_{OUT} / V_{IN} . To minimize coupling to sensitive circuitry, the PC board copper area connected to this pin should be kept a minimum.

Feedback

Senses the regulated output voltage to complete the feedback loop.

ON/OFF

Allows the switching regulator circuit to be shut down using logic level signals, thus dropping the total input supply current to approximately 150 μ A. Pulling this pin below a threshold voltage of approximately 1.3V turns the regulator on, and pulling this pin above 1.3V (up to a maximum of 40V) shuts the regulator down. If this shutdown feature is not needed, the ON/OFF pin can be wired to the ground pin, or it can be left open. In either case the regulator will be in the ON condition.

Thermal Considerations

The AP1501 is available in the 5-pin surface mount TO-263 and TO-220.

Under most conditions, the TO-220 package requires a heat sink. The size of the heat sink depends on the input voltage, the output voltage, the load current, and the ambient temperature. The AP1501 junction temperature rises above ambient temperature for a 3A load and different input and output voltages. The data for these curves was taken with the AP1501 (TO-220 package) operating as a buck switching regulator in an ambient temperature of 25°C (still air). These temperature rise numbers are all approximate and there are many factors that can affect these temperatures. Higher ambient temperatures require more heat sinking.

The TO-263 surface mount package tab is designed to be soldered to the copper on a printed circuit board. The copper and the board are the heat sink for this package and the other heat producing components, such as the catch diode and inductor. The PC board copper area that the package is soldered to should be at least 0.4 in², and ideally should have 2 or more square inches of 2 oz. Additional copper area improves the thermal characteristics, but with copper areas greater than approximately 6 in², only small improvements in heat dissipation are realized. If further thermal improvements are needed, double-sided multilayer PC boards with large copper areas and/or airflow are recommended.

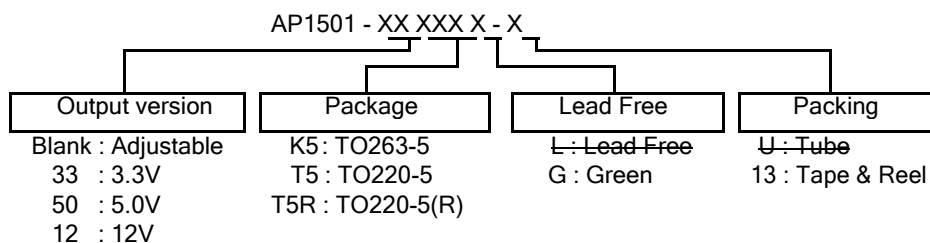
The AP1501 (TO-263 package) junction temperature rises above ambient temperature with a 2A load for various input and output voltages. This data was taken with the circuit operating as a buck switching regulator with all components mounted on a PC board to simulate the junction temperature under actual operating conditions. This curve can be used for a quick check for the approximate junction temperature for various conditions, but be aware that there are many factors that can affect the junction temperature. When load currents higher than 2A are used, double-sided or multilayer PC boards with large copper areas and/or airflow might be needed, especially for high ambient temperatures and high output voltages.

For the best thermal performance, wide copper traces and generous amounts of printed circuit board copper should be used in the board layout. (One exception to this is the output (switch) pin, which should not have large areas of copper.) Large areas of copper provide the best transfer of heat (lower thermal resistance) to the surrounding air, and moving air lowers the thermal resistance even further.

Package thermal resistance and junction temperature rise numbers are all approximate, and there are many factors that will affect these numbers. Some of these factors include board size, shape, thickness, position, location, and even board temperature. Other factors are trace width, total printed circuit copper area, copper thickness, the board being single or double-sided, the board being multilayered, and the amount of solder on the board. The effectiveness of the PC board to dissipate heat also depends on the size, quantity, and spacing of other components on the board, as well as whether the surrounding air is still or moving.

Furthermore, some of these components such as the catch diode will add heat to the PC board, and the heat can vary as the input voltage changes. For the inductor, depending on the physical size, type of core material, and the DC resistance, it could either add heat to the board or act as a heat sink taking heat away from the board.

Ordering Information

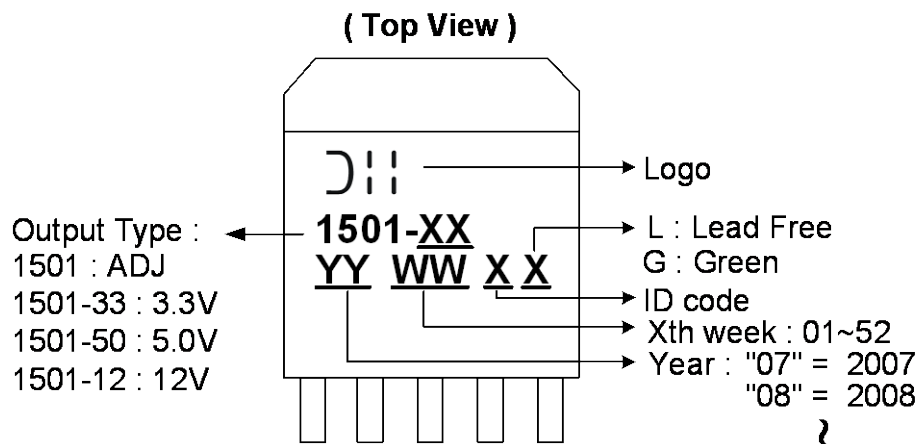


Device (Note 4)	Voltage	Package Code	Package (Note 7)	Lead Free/ Green	Quantity	Part Number Suffix		Status (Note 6)
						Tube	13" Tape and reel	
AP1501-50K5G-13	50	K5	TO263-5	Green	800	NA	-13	Active
AP1501-K5G-13	ADJ	K5	TO263-5	Green	800	NA	-13	Active
AP1501-12K5G-13	12	K5	TO263-5	Green	800	NA	-13	NRND
AP1501-33K5G-13	33	K5	TO263-5	Green	800	NA	-13	NRND

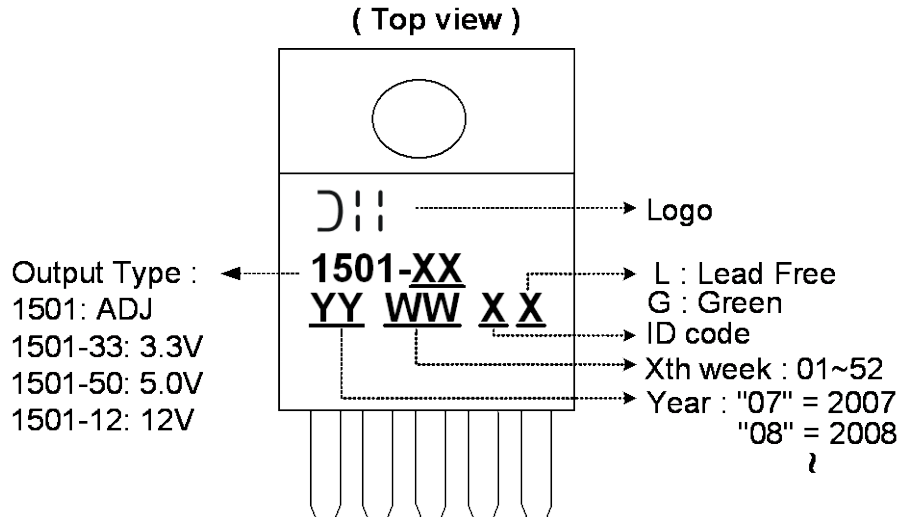
- Notes:
- AP1501-50K5G-13 and AP1501-K5G-13 are Active. All other versions are NRND or EOL.
For recommended alternatives to NRND/EOL devices, [Contact Us](#).
 - For packaging details, go to our website at:
<https://www.diodes.com/design/support/packaging/diodes-packaging/diodes-package-outlines-and-pad-layouts/>.

Marking Information

(1) TO263-5



(2) TO220-5



Please see <http://www.diodes.com/package-outlines.html> for the latest version.

TO263-5		
Dim	Min	Max
A	4.07	4.85
A1	1.14	1.40
b	0.66	1.02
c	0.36	0.64
D	8.65	9.65
E	9.78	10.54
e	1.57	1.85
L	14.61	15.88
L1	2.29	2.79
L2	-	2.92
All Dimensions in mm		

Technical drawing of a seat cushion assembly, showing front and side views with dimensions.

Front View (Left):

- Overall width: E
- Overall height: D
- Top width of the upper section: E
- Top width of the lower section: e_1
- Top width of the base: e
- Top width of the base: b
- Top width of the base: b_1
- Top width of the base: L_1
- Top width of the base: L
- Top width of the base: $\varnothing P$
- Top width of the base: Q
- Top width of the base: J

Side View (Right):

- Overall height: D_1
- Top width of the upper section: A
- Top width of the lower section: F
- Top width of the base: C
- Top width of the base: J_1
- Top width of the base: SEATING PLANE

TO220-5		
Dim	Min	Max
A	3.55	4.85
b	0.51	1.14
b1	1.14	1.78
C	0.31	1.14
D	14.20	16.50
D1	5.84	6.86
E	9.78	10.54
e	1.6	1.8
e1	6.6	7.0
F	0.51	1.40
J1	2.03	2.92
L	12.72	14.72
L1	3.66	6.35
P	3.53	4.09
Q	2.54	3.43
All Dimensions in mm		

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

The diagram illustrates a 2D grid structure. A large square cell is shown with a width labeled X and a height labeled Y . Inside this square is a smaller square with a width labeled X_1 and a height labeled Y_1 . Below the large square, there is a row of four smaller rectangular cells. The height of these cells is labeled Y_2 . The width of the row is labeled C . The distance from the right edge of the row to the right edge of the large square is labeled X_1 .

Dimensions	Value (in mm)
X	10.9
X1	1.05
Y	15.7
Y1	9.1
Y2	2.5
C	1.7

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